



## Material Content Data Sheet



<b>Sales Product Name</b>		BFR 193W H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000757646						
<b>Package</b>		PG-SOT323-3-1		<b>Weight*</b>		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.005	0.08		757	
	non noble metal	tin	7440-31-5	0.001	0.02		195	
	inorganic material	silicon	7440-21-3	0.016	0.26	0.36	2640	3592
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1323	
	non noble metal	copper	7440-50-8	2.617	43.92	44.10	439219	441071
wire	noble metal	gold	7440-57-5	0.008	0.13	0.13	1318	1318
encapsulation	organic material	carbon black	1333-86-4	0.032	0.53		5301	
	plastics	epoxy resin	-	0.679	11.40		113964	
	inorganic material	silicondioxide	60676-86-0	2.448	41.08	53.01	410802	530067
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22272	22272
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1680	1680
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com